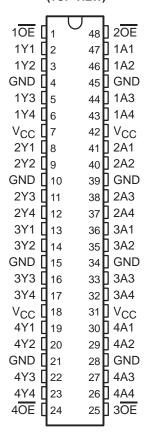
SCAS137C - JULY 1989 - REVISED NOVEMBER 1996

- **Members of the Texas Instruments** Widebus™ Family
- Inputs Are TTL-Voltage Compatible
- 3-State Outputs Drive Bus Lines or Buffer **Memory Address Registers**
- Flow-Through Architecture Optimizes **PCB Layout**
- Distributed V<sub>CC</sub> and GND Pin Configuration **Minimizes High-Speed Switching Noise**
- **EPIC** ™ (Enhanced-Performance Implanted CMOS) 1-µm Process
- 500-mA Typical Latch-Up Immunity at
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Packages Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Packages Using 25-mil Center-to-Center **Spacings**

### description

The SN54ACT16240 and 74ACT16240 are 16-bit buffers or line drivers designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. The devices can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. These devices provide inverting outputs and symmetrical active-low output-enable  $(\overline{OE})$  inputs.

SN54ACT16240 . . . WD PACKAGE 74ACT16240 . . . DL PACKAGE (TOP VIEW)



The 74ACT16240 is packaged in TI's shrink small-outline package, which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The SN54ACT16240 is characterized for operation over the full military temperature range of -55°C to 125°C. The 74ACT16240 is characterized for operation from -40°C to 85°C.

#### **FUNCTION TABLE** (each section)

INPU	JTS	OUTPUT
OE	Α	Υ
L	Н	L
L	L	Н
Н	Χ	Z

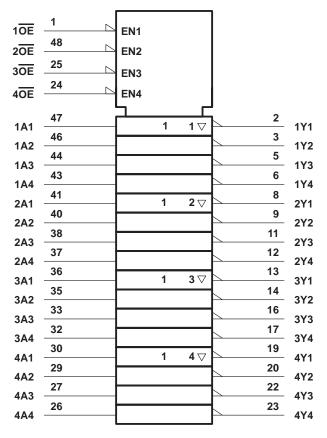


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STRUMENTS

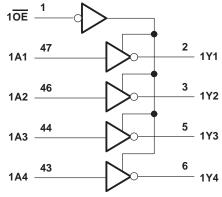
## logic symbol†

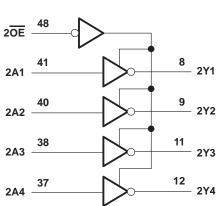


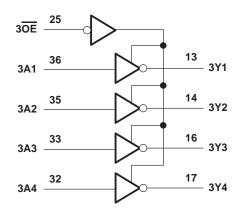
 $<sup>\</sup>ensuremath{^{\dagger}}$  This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

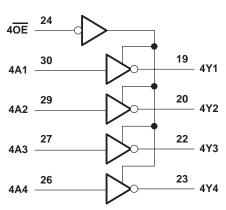


## logic diagram (positive logic)









# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)0	$.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Output voltage range, V <sub>O</sub> (see Note 1)0	$.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ )	±20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> )	±50 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	±50 mA
Continuous current through V <sub>CC</sub> or GND	±400 mA
Maximum package power dissipation at T <sub>A</sub> = 55°C (in still air) (see Note 2): DL package	1.2 W
Storage temperature range, T <sub>stg</sub>	−65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.



# SN54ACT16240, 74ACT16240 16-BIT BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

SCAS137C - JULY 1989 - REVISED NOVEMBER 1996

## recommended operating conditions (see Note 3)

		SN54ACT16240			74	10	l <sub>UNIT</sub>	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2		7	2			V
V <sub>IL</sub>	Low-level input voltage		Ž	0.8			0.8	V
VI	Input voltage	0	200	VCC	0		VCC	V
Vo	Output voltage	0	1	VCC	0		VCC	V
Іон	High-level output current		3	-24			-24	mA
loL	Low-level output current	,O/	5	24			24	mA
Δt/Δν	Input transition rise or fall rate	0		10	0		10	ns/V
T <sub>A</sub>	Operating free-air temperature	<del>-</del> 55		125	-40		85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CONDITIONS	V	T	չ = 25°C	;	SN54AC	T16240	74ACT	16240	UNIT
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
	Jan - 50 u A	4.5 V	4.4			4.4		4.4		
	IOH = -50 μA	5.5 V	5.4			5.4		5.4		
\/o	I <sub>OH</sub> = -24 mA	4.5 V	3.94			3.7		3.8		V
Voн	10H = -24 IIIA	5.5 V	4.94			4.7		4.8		V
	$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V				3.85				
	$I_{OH} = -75 \text{ mA}^{\dagger}$							3.85		
	I <sub>OL</sub> = 50 μA	4.5 V			0.1		0.1		0.1	٧
	ΙΟΣ = 50 μΑ	5.5 V			0.1		0.1		0.1	
Voi	I <sub>OL</sub> = 24 mA	4.5 V			0.36		0.5		0.44	
VOL	10L = 24 111A	5.5 V			0.36	(2)	0.5		0.44	
	I <sub>OL</sub> = 50 mA <sup>†</sup>	5.5 V				200	1.65			
	I <sub>OL</sub> = 75 mA <sup>†</sup>	5.5 V				25			1.65	
lį	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	μΑ
loz	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±10		±5	μΑ
ICC	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			8		160		80	μΑ
∆ICC <sup>‡</sup>	One input at 3.4 V, Other inputs at VCC or GND	5.5 V			0.9		1		1	mA
C <sub>i</sub>	$V_I = V_{CC}$ or GND	5.5 V		4.5						pF
Co	$V_O = V_{CC}$ or GND	5 V		12						pF

<sup>†</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.



<sup>‡</sup>This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V<sub>CC</sub>.

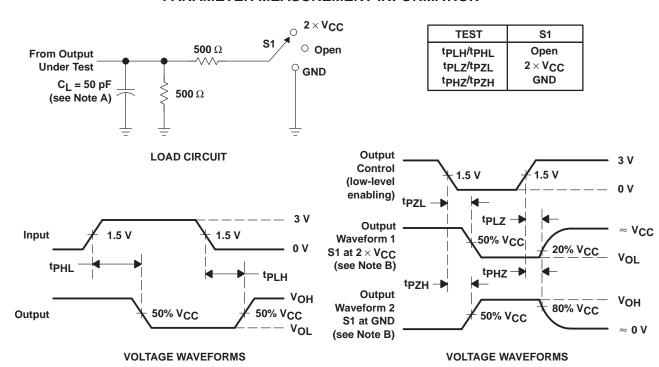
# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	T,	չ = 25°C	;	SN54ACT	16240	74ACT	UNIT	
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
t <sub>PLH</sub>	А		2.3	5	7.7	2	9.5	2.3	8.5	ns
<sup>t</sup> PHL	A	'	4.1	6.7	9.2	3	11.5	4.1	10.2	115
<sup>t</sup> PZH	<u></u>	V	2.6	5.6	8.5	2	10.1	2.6	9.4	ns I
t <sub>PZL</sub>	OE	Y	3.3	6.7	10.2	2.5	12.2	3.3	11.4	
<sup>t</sup> PHZ		Y	5.9	8.3	11	4.5	12.7	5.9	12	ns
t <sub>PLZ</sub>	ŌĒ		5.1	7.4	9.9	4	12	5.1	10.7	

## operating characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C

	PARAMETER	TEST CO	TYP	UNIT		
C <sub>pd</sub> Power dissipation capacit	Down dissination conscitance nor driver	Outputs enabled	C. 50 pF	f = 1 MHz	38	pF
	Fower dissipation capacitance per univer	Outputs disabled	C <sub>L</sub> = 50 pF,	I = I IVIMZ	9	

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_f = 3 \text{ ns}$ ,  $t_f = 3 \text{ ns}$ .
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





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#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
74ACT16240DL	LIFEBUY	SSOP	DL	48	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16240	
74ACT16240DLR	ACTIVE	SSOP	DL	48	1000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16240	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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# **PACKAGE MATERIALS INFORMATION**

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## TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

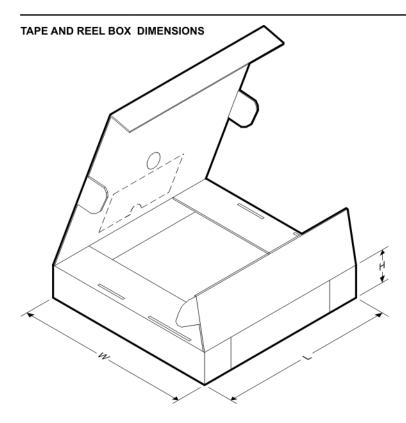
## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



### \*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ACT16240DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

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#### \*All dimensions are nominal

Ī	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
	74ACT16240DLR	SSOP	DL	48	1000	367.0	367.0	55.0

# PACKAGE MATERIALS INFORMATION

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## **TUBE**

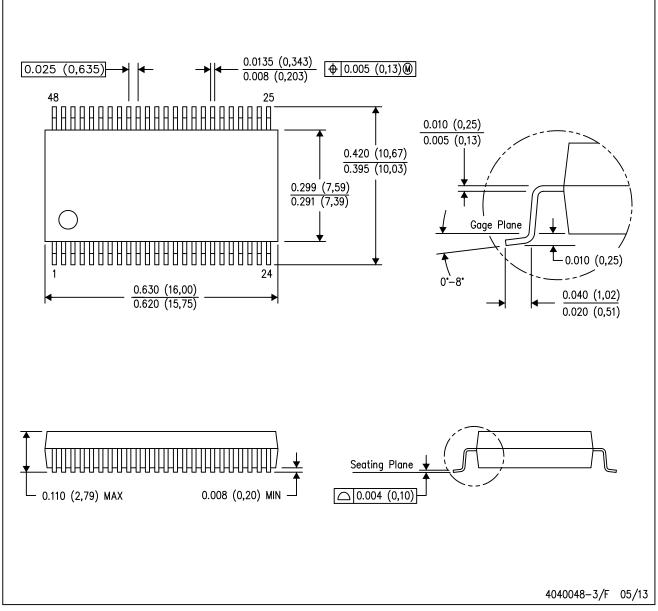


#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
74ACT16240DL	DL	SSOP	48	25	473.7	14.24	5110	7.87

# DL (R-PDSO-G48)

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

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